# RESIN 665

NEW

## Cold setting resin for sample recovery.

**Mounting is a step in metallographic sample preparation which enables samples to be ground and polished more ergonomically. Embedding the sample in a resin is usually irreversible and recovering the sample (if necessary) after embedding proves almost impossible.**

### Description

Resin 665 is a cold mounting resin that has the unique ability to dissolve in acetone. This ability is transformed into a sustainable functionality to recover metallographic specimens after mounting. After metallographic processing of costly materials such as noble metals, it is often important from an economic an technical perspective to recover the samples from the mounting resin.

### Characteristics

Resin 665 is an easy to use acrylic bi-componant resin (powder and liquid). During curing, the mixture can reach up to 105°C (embedding mould 30 mm). The hardness of the cured resin is about 80 Shore D. Like LAM PLAN's other acrylic cold setting resins (Resin 605 and Resin 609), Resin 665 can be used to embed all types of material for metallographic analysis.

### Recovering the sample

There are two ways to recover the specimens from the mount:

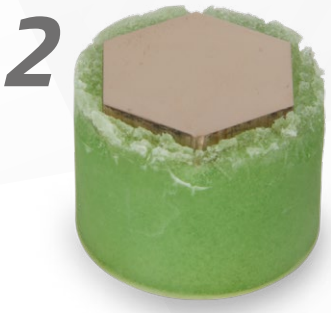
#### 1. Using Acetone:

The sample can be placed into a closed receptacle containing aceton at ambient temperature (do not heat the acetone). Make sure that the sample is totally submerged in the liquid. (approximately 150 ml of acetone is recommended to dissolve a 30 mm mount). Depending on the size of the mount, it can take from a few hours to three days for the enrobing resin to dissolve.

#### 2. Using heat:

This method can only be used if the specimens are resistant to temperatures above 150°C. The embedded sample can be placed in an oven preheated to 150°C. In a few hours depending the sized of the mount, the resin softens allowing the sample to be ejected mechanically.


*Coating after polishing*




*Dissolution with acetone*


*Recover your intact sample*

| Technical Data | RESIN 665 |
|---|---|
| Packaging | Kit powder 1000 g + catalyst 500 ml<br>Code 06 00665 00 |
| | Powder 1000 g - Code 06 01665 00 |
| | Catalyst 500 ml - Code 06 02665 00 |
| Dosage | 2 parts powder to 1 part liquid |
| Polymerisation time | 10 to 15 min. |
| Polymerisation temperature | Maximum 105°C |
| Hardness | 80 Shore D |
| Dissolution | Acetone |
| Demoulding temperature | 150°C |

**Safety data sheets**

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